Electronic Patent Application Fee Transmittal							
Application Number:	10710662						
Filing Date:	27-	27-Jul-2004					
Title of Invention:	[M]	[METHOD OF RELIEVING WAFER STRESS]					
First Named Inventor/Applicant Name:	Jui	Jui-Tsen Huang					
Filer:	Be	Belinda Lee/Shih-Mei Lin					
Attorney Docket Number:	12:	12336-US-PA					
Filed as Large Entity	•						
Utility under 35 USC 111(a) Filing Fees							
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							
Utility Appl issue fee		1501	1	1510	1510		
Publ. Fee- early, voluntary, or normal		1504	1	300	300		

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
	Total in USD (\$)			1810